

FEATURES:

- Ideal for surface mount applications
- Easy pick and place
- Built-in strain relief
- Glass passivated Chip

MECHANICAL DATA

Case : Molded plastic use UL 94V-0 recognized flame retardant epoxy

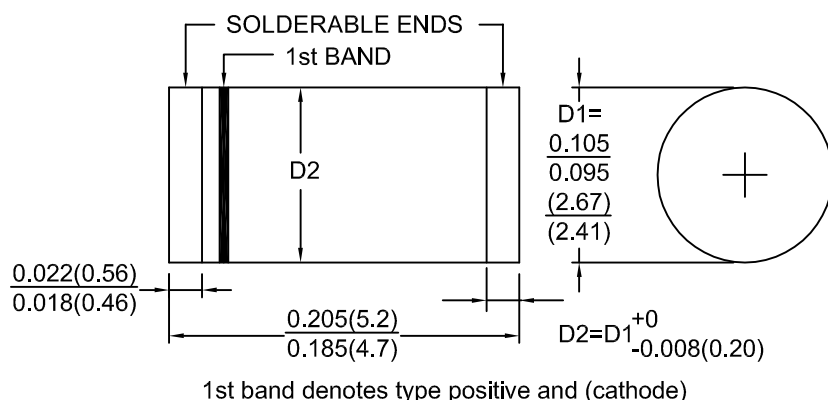
Terminals : Plated terminals, solderable per MIL-STD-202, Method 208 guaranteed

Polarity : Silver color band on body denotes cathode

Mounting Position : Any

Weight : 0.116 grams, 0.0046 ounce

MELF / DO-213AB



Dimensions in inches and (millimeters)

MAXIMUM RATINGS AND ELECTRICAL CHARACTERISTICS

Rating at 25°C ambient temp. unless otherwise specified.

Single phase, half sine wave, 60 Hz, resistive or inductive load.

For capacitive load, derate current by 20 %.

Characteristic	Symbol	SFM 101	SFM 102	SFM 103	SFM 104	SFM 105	SFM 106	Units
Maximum recurrent peak reverse voltage	V _{RRM}	50	100	200	300	400	600	Volts
Maximum RMS voltage	V _{RMS}	35	70	140	212	280	420	Volts
Maximum DC blocking voltage	V _{DC}	50	100	200	300	400	600	Volts
Maximum average forward rectified current at T _L = 55 °C	I _(AV)	1.0						Amp
Peak forward surge current 8.3ms single half sine-wave superimposed on rated load(JEDEC Method)	I _{FSM}	30.0						Amps
Maximum instantaneous forward voltage at 1.0 A	V _F	1.0			1.3		1.7	Volts
Maximum DC reverse current at rated DC blocking voltage Ta=25°C Ta=100°C	I _R	5.0 100						μ A
Maximum reverse recovery time (NOTE 1)	t _{rr}	35						nS
Operating temperature range	T _J	-65 to +150						°C
Storage temperature range	T _{stg}	-65 to +150						°C

NOTES:

- (1) Reverse recovery test condition : I_F=0.5A, I_R=1.0A, I_{rr}=0.25A
- (2) Measured at 1.0 MHz and applied reverse voltage of 4.0 Volts
- (3) P.C.B. mounted on 0.2x0.2"(5.0x5.0mm) copper pad area

FIG.1 - FORWARD CURRENT DERATING CURVE

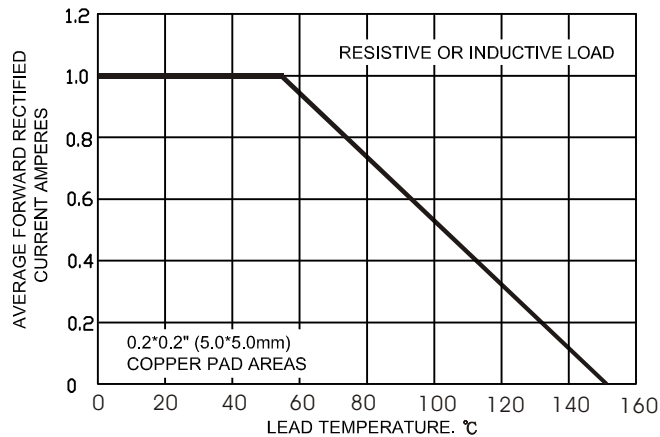


FIG.2 - MAXIMUM NON-REPETITIVE PEAK FORWARD SURGE CURRENT

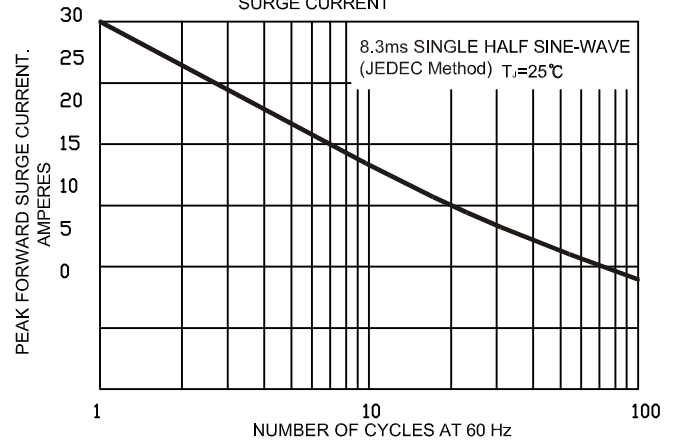


FIG.3 - TYPICAL INSTANTANEOUS FORWARD CHARACTERISTIC

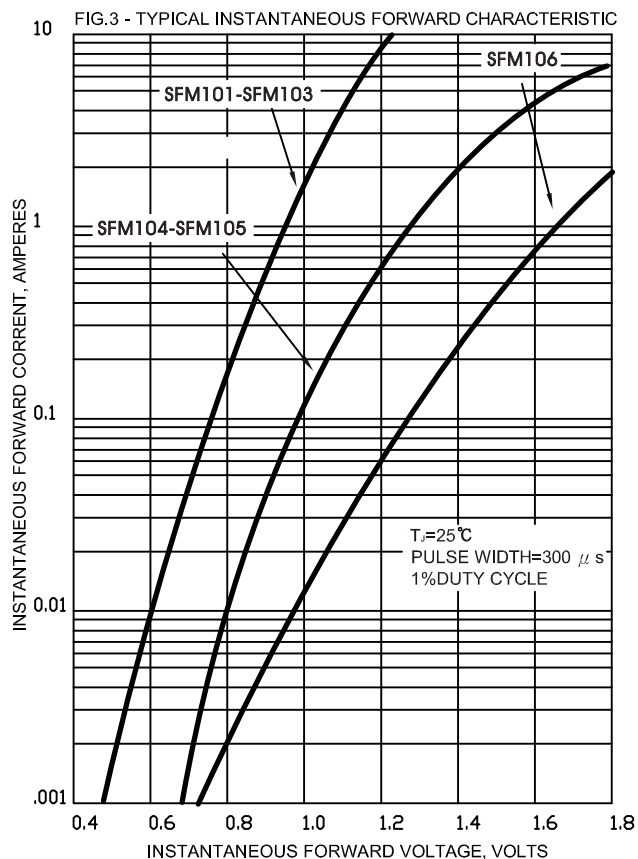


FIG.4-TYPICAL REVERSE LEAKAGE CHARACTERISTICS

